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SGA3363Z

DC to 5500 MHz, CASCADABLE SiGe HBT MMIC AMPLIFIER

Package: SOT-363

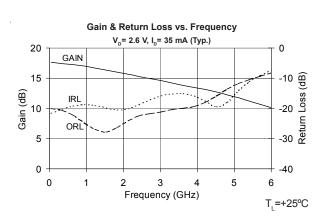




Product Description

The SGA3363Z is a high performance SiGe HBT MMIC Amplifier. A Darlington configuration featuring one-micron emitters provides high F_{T} and excellent thermal performance. The heterojunction increases breakdown voltage and minimizes leakage current between junctions. Cancellation of emitter junction non-linearities results in higher suppression of intermodulation products. Only two DC-blocking capacitors, a bias resistor, and an optional RF choke are required for operation.





Features

- High Gain: 15.9dB at 1950MHz
- Cascadable 50Ω
- Operates from Single Supply
- Low Thermal Resistance Package

Applications

- PA Driver Amplifier
- Cellular, PCS, GSM, UMTS
- IF Amplifier
- Wireless Data, Satellite

Parameter	Specification			Unit	Condition	
Farameter	Min.	Тур.	Max.	Ullit	Condition	
Small Signal Gain	15.5	17.5	19.5	dB	850MHz	
		15.9		dB	1950MHz	
		15.3		dB	2400MHz	
Output Power at 1dB Compression		11.6		dBm	850MHz	
		10.5		dBm	1950MHz	
Output Third Intercept Point		25.4		dBm	850MHz	
		23.1		dBm	1950MHz	
Bandwidth Determined by Return Loss		5500		MHz	>10 dB	
Input Return Loss		20.4		dB	1950MHz	
Output Return Loss		25.5		dB	1950MHz	
Noise Figure		3.5		dB	1950MHz	
Device Operating Voltage	2.3	2.6	2.9	V		
Device Operating Current	31	35	39	mA		
Thermal Resistance (Junction - Lead)		255		°C/W		

Test Conditions: $V_S = 5V$, $I_D = 35$ mA Typ., OIP_3 Tone Spacing = 1MHz, P_{OUT} per tone = -5 dBm, $R_{BIAS} = 68\Omega$, $T_L = 25$ °C, $Z_S = Z_L = 50\Omega$



Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Current (I _D)	70	mA
Max Device Voltage (V _D)	4	V
Max RF Input Power	+18	dBm
Max Junction Temp (T _J)	+150	°C
Operating Temp Range (T _L)	-40 to +85	°C
Max Storage Temp	+150	°C

Operation of this device beyond any one of these limits may cause permanent damage. For reliable continuous operation, the device voltage and current must not exceed the maximum operating values specified in the table on page one. Bias Conditions should also satisfy the following expression: $I_D V_D < (T_J - T_L) / R_{TH}, j - I_D > I_D >$



Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

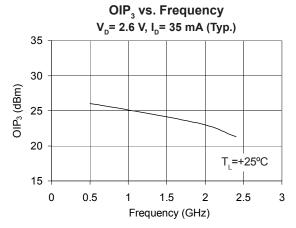
RoHS status based on EUDirective 2002/95/EC (at time of this document revision).

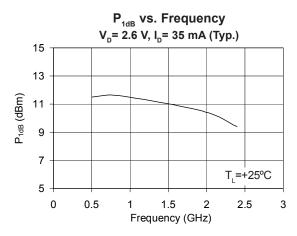
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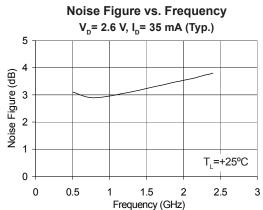
Typical Performance at Key Operating Frequencies

Parameter	Unit	100	500	850	1950	2400	3500
		MHz	MHz	MHz	MHz	MHz	MHz
Small Signal Gain	dB	17.7	17.6	17.5	15.9	15.3	14.0
Output Third Order Intercept Point	dBm		26.0	25.4	23.1	21.3	
Output Power at 1dB Compression	dBm		11.5	11.6	10.5	9.4	
Input Return Loss	dB	21.3	19.7	18.8	20.4	18.8	15.1
Output Return Loss	dB	20.2	21.3	23.9	25.5	22.5	20.1
Reverse Isolation	dB	20.7	20.7	20.8	21.0	20.8	20.1
Noise Figure	dB		3.1	2.9	3.5	3.8	

 $Test \ Conditions: V_S = 5V, \ I_D = 35 \ mA \ Typ., \ OIP_3 \ Tone \ Spacing = 1 \ MHz, \ P_{OUT} \ per \ tone = -5 \ dBm, \ R_{BIAS} = 68 \ \Omega, \ T_L = 25 \ ^\circ C, \ Z_S = Z_L = 50 \ \Omega$

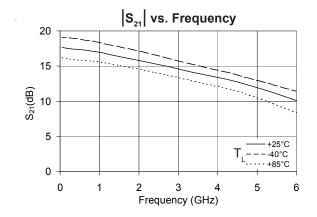


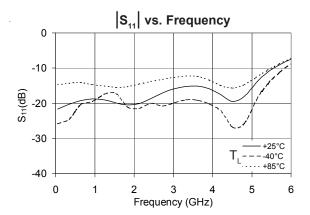


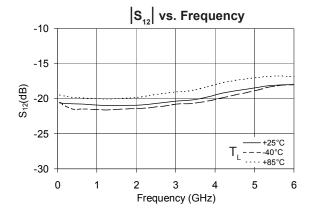


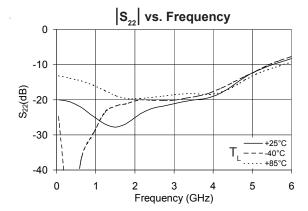


Typical RF Performance Over Temperature (Bias: $V_D = 2.6V$, $I_D = 35 \text{ mA}$)





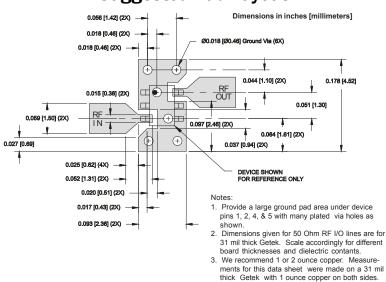






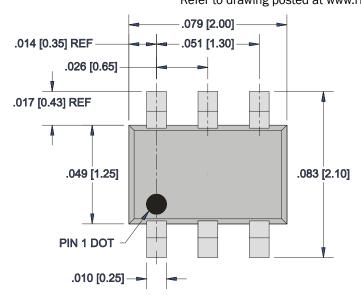
Pin	Function	Description
3	RF IN	RF input pin. This pin requires the use of an external DC-blocking capacitor chosen for the frequency of operation.
1, 2, 4, 5	GND	Connection to ground. For optimum RF performance, use via holes as close to ground leads as possible to reduce lead inductance.
6	RF OUT/BIAS	RF output and bias pin. DC voltage is present on this pin, therefor a DC-blocking capacitor is necessary for proper operation.

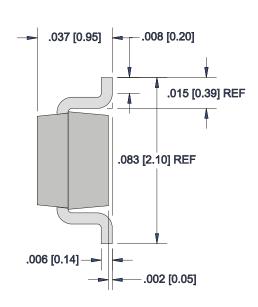
Suggested Pad Layout



Package Drawing

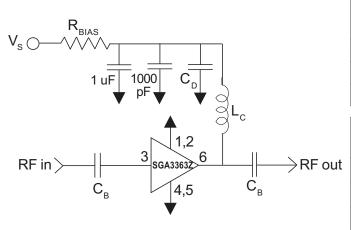
Dimensions in inches (millimeters)
Refer to drawing posted at www.rfmd.com for tolerances.







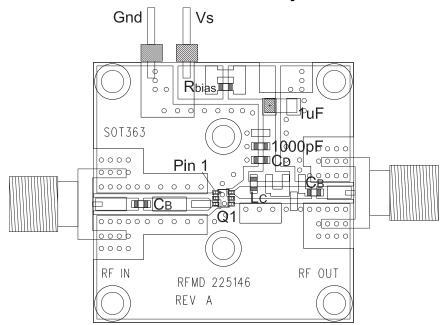
Application Schematic



Reference	Frequency (Mhz)						
Designator	500	850	1950	2400	3500		
C _B	220 pF	100 pF	68 pF	56 pF	39 pF		
C _D	100 pF	68 pF	22 pF	22 pF	15 pF		
L _c	68 nH	33 nH	22 nH	18 nH	15 nH		

Recommended Bias Resistor Values for I_D =35mA R_{BIAS} =(V_S - V_D) / I_D				
Supply Voltage(V _S)	5 V	8 V	10 V	12 V
R _{BIAS}	68 Ω	150 Ω	200Ω	270 Ω
Note: $R_{\mbox{\tiny BMS}}$ provides DC bias stability over temperature.				

Evaluation Board Layout



Mounting Instructions:

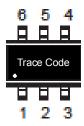
- 1. Use a large droung pad area near device pins 1, 2, 4, and 5 with plated through-holes as shown.
- 2. We recommend 1 or 2 ounces copper. Measurements for this data sheet were made on a 31mil thick FR-4 board with 1 ounce copper on both sides.



Part Identification Marking



Alternate Marking with Trace Code Only



Ordering Information

Ordering Code	Description
SGA3363Z	7" Reel with 3000 pieces
SGA3363ZSQ	Sample bag with 25 pieces
SGA3363ZSR	7" Reel with 100 pieces
SGA3363ZPCK1	850MHz, 5V Operation PCBA with 5-piece sample bag